

ABSTRACT OF THE DISCLOSURE

A first waveguide groove is formed in a sidewall of a main casing housing a first circuit board, and a second waveguide groove is formed in a sidewall of a sub-casing hermetically housing a second circuit board such that the first waveguide groove is in continuous connection with the second waveguide groove. Further, a lid is attached to the sidewall of the main casing so as to cover the first and the second waveguide grooves, and a probe provided on the second circuit board protrudes into the second waveguide groove. In addition, an inclined plane is formed at an end of the first waveguide groove so as to be in continuous connection with a through-hole provided in the lid.

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